## HX318C10FWK2/8

8GB (4GB 512M x 64-Bit x 2 pcs.)
DDR3-1866 CL10 240-Pin DIMM Kit


## DESCRIPTION

HyperX HX318C10FWK2/8 is a kit of two 512M x 64-bit (4GB) DDR3-1866 CL10 SDRAM (Synchronous DRAM) 1Rx8 memory modules, based on eight 512M x 8-bit DDR3 FBGA components per module. Total kit capacity is 8GB. Each module kit has been tested to run at DDR3-1866 at a low latency timing of 10-11-10 at 1.5 V . Additional timing parameters are shown in the PnP Timing Parameters section below. The JEDEC standard electrical and mechanical specifications are as follows:

Note: The PnP feature offers a range of speed and timing options to support the widest variety of processors and chipsets. Your maximum speed will be determined by your BIOS.

## PnP JEDEC TIMNG PARAMEIERS:

- DDR3-1866 CL10-11-10 @1.5V
- DDR3-1600 CL9-10-9 @1.5V
- DDR3-1333 CL8-9-8 @1.5V

SPECIFICATIONS

| CL(IDD) | 10 cycles |
| :--- | :--- |
| Row Cycle Time (tRCmin) | 44.75 ns (min.) |
| Refresh to Active/Refresh <br> Command Time (tRFCmin) | 260 ns (min.) |
| Row Active Time (tRASmin) | 32.125 ns (min.) |
| Maximum Operating Power | TBD W (per module) |
| UL Rating | $94 \mathrm{~V}-0$ |
| Operating Temperature | $0^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ |
| Storage Temperature | $-55^{\circ} \mathrm{C}$ to $+100^{\circ} \mathrm{C}$ |
| *Power will vary depending on the SDRAM used. |  |

## FEATURES

- JEDEC standard 1.5V (1.425V ~1.575V) Power Supply
- $\mathrm{VDDQ}=1.5 \mathrm{~V}(1.425 \mathrm{~V} \sim 1.575 \mathrm{~V})$
- 933MHz fCK for $1866 \mathrm{Mb} / \mathrm{sec} / \mathrm{pin}$
- 8 independent internal bank
- Programmable CAS Latency: 13, 11, 10, 9, 8, 7, 6
- Programmable Additive Latency: 0, CL - 2, or CL - 1 clock
- 8-bit pre-fetch
- Burst Length: 8 (Interleave without any limit, sequential with starting address "000" only), 4 with tCCD $=4$ which does not allow seamless read or write [either on the fly using A12 or MRS]
- Bi-directional Differential Data Strobe
- Internal(self) calibration : Internal self calibration through ZQ pin (RZQ : 240 ohm $\pm$ 1\%)
- On Die Termination using ODT pin
- Average Refresh Period 7.8 us at lower than TCASE $85^{\circ} \mathrm{C}$, 3.9 us at $85^{\circ} \mathrm{C}<$ TCASE $\leq 95^{\circ} \mathrm{C}$
- Asynchronous Reset
- Height 1.291 " ( 32.80 mm ) w/heatsink, single sided component

Continued >>

MODULE WITH HEAT SPREADER


## MODULE DIMENSIONS



FOR MORE INFORMATION, GO TO WWW.KINGSTON.COM/HYPERX

All Kingston products are tested to meet our published specifications. Some motherboards or system configurations may not operate at the published HyperX memory speeds and timing settings. Kingston does not recommend that any user attempt to run their computers faster than the published speed. Overclocking or modifying your system timing may result in damage to computer components.

